IPC ASSOCIATION ELECTRONIC	Material Composition Connecting © Copyright 2005. Il international and Par	PC, Bannockb	urn, Illinois. A	all rights reserved un	nder both	This docume level parts, t	ent is a declar the declaration	ration of n encon	f the substances mpasses all lowe	within the r level ma	e manufactur terials for w	er listed it	em. Note: i	f the item is an as has engineering	sembly with loweresponsibility.
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					eous Materi	als and M	fg Informati	ion		
Supplie	r Information														
Company name* Company unique ID				ique ID	Unique I			aique ID Authority				Response Date*			
onsemi												2024-05-17			
Contact N	Name	Title - Contact]	Phone - Contact*				Email - Contact*					
Product-l	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Authorize	ed Representative*	Title - Representative			1	Phone - Representative*				Email - Representative*					
Product-1	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Da	e Date Version Manufacturing Site		ring Site	1	Weight*	UOM	Unit Type	
		LM385Z-2.5G ANA MIC		ANA MICROPWI	OPWR V-REG DIODE		2024-05-17			CNF		1	198.01	mg	Each
Manufa	acturing Proccess Information	tion													
	Terminal Plating / Grid Array Material Terminal Plating / Grid Array Material		Germinal Base Alloy J-STD-020 MS		_ Rating	Peak Process Body Temperat		ture Max Time at Peak Temper		Temperat	ure Numb	er of Reflow Cyo	eles		
	Matte Tin (Sn) - annealed		CU Alloy NA			0 C		30 seco		secon	ds 3				
Comments	S														
				·							·				·
or more	information regarding material	composition	please refer to	page 3										·	

RoHS Material Composition Declaration			Declaration Type *	Detail	ed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).												
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of							
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted							
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all							
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.2	mg	Supplier	Silicon (Si)	7440-21-3		3.2	mg
Die Attach	5.15	mg	Supplier	Silver (Ag)	7440-22-4		3.8625	mg
			Supplier	Epoxy resins	129915-35-1		1.2875	mg
Lead Frame	80.67	mg	Supplier	Silver (Ag)	7440-22-4		0.4033	mg
			Supplier	Copper (Cu)	7440-50-8		80.2666	mg
Mold Compound-Black	106.15	mg		Metal Hydroxide	proprietary data		5.3075	mg
			Supplier	Carbon Black (C)	1333-86-4		1.0615	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		79.6125	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		10.615	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		9.5535	mg
Plating	2.74	mg	Supplier	Tin (Sn)	7440-31-5		2.74	mg
Wire Bond - Au	0.1	mg	Supplier	Gold (Au)	7440-57-5		0.1	mg